

SOT143B

plastic surface-mounted package; 4 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT143B
Package type industry code	SOT143B
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.8	-	2.9	3	mm
E	package width	1.2	-	1.3	1.4	mm
A	seated height	0.9	-	1	1.1	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

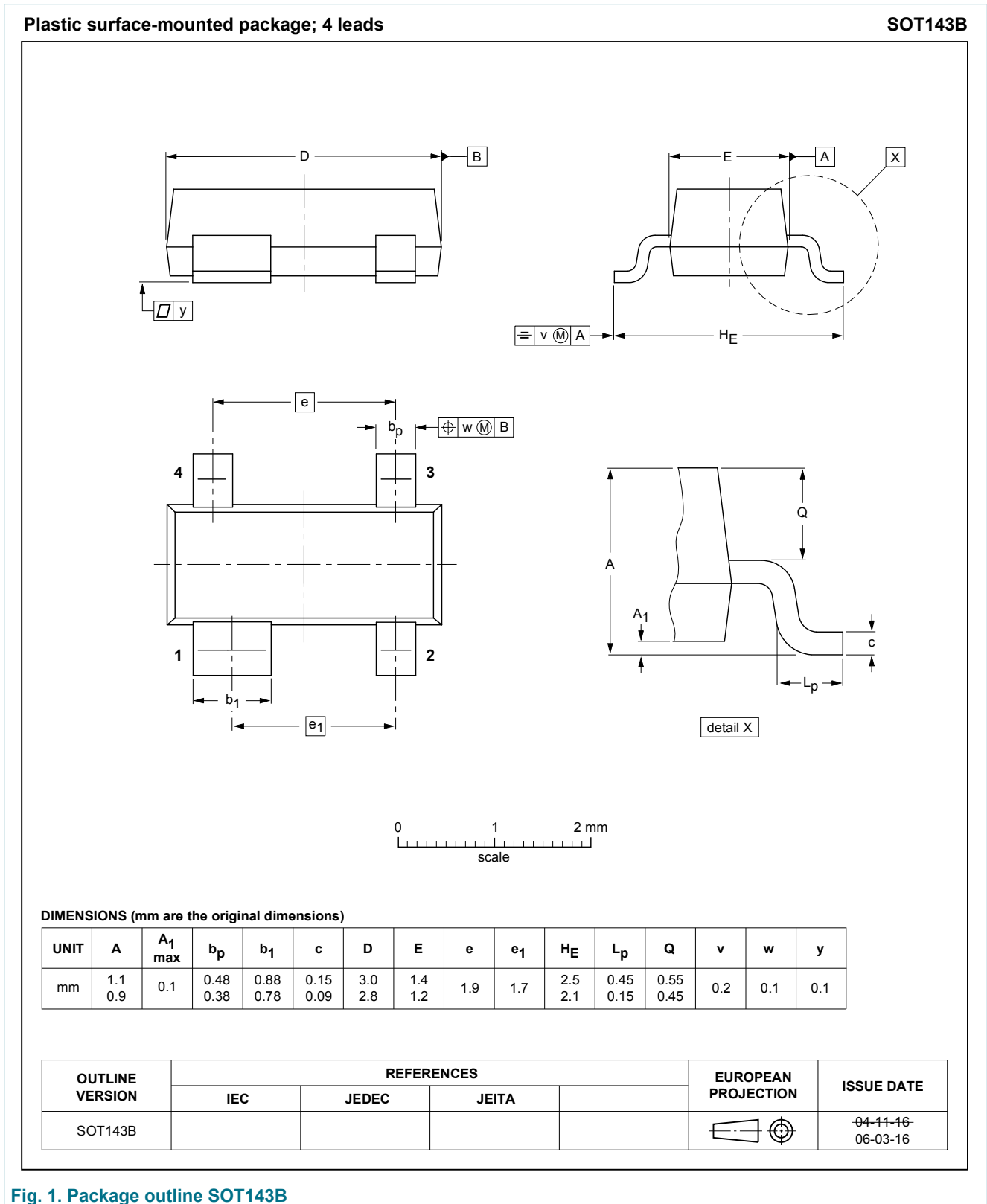


Fig. 1. Package outline SOT143B

3. Soldering

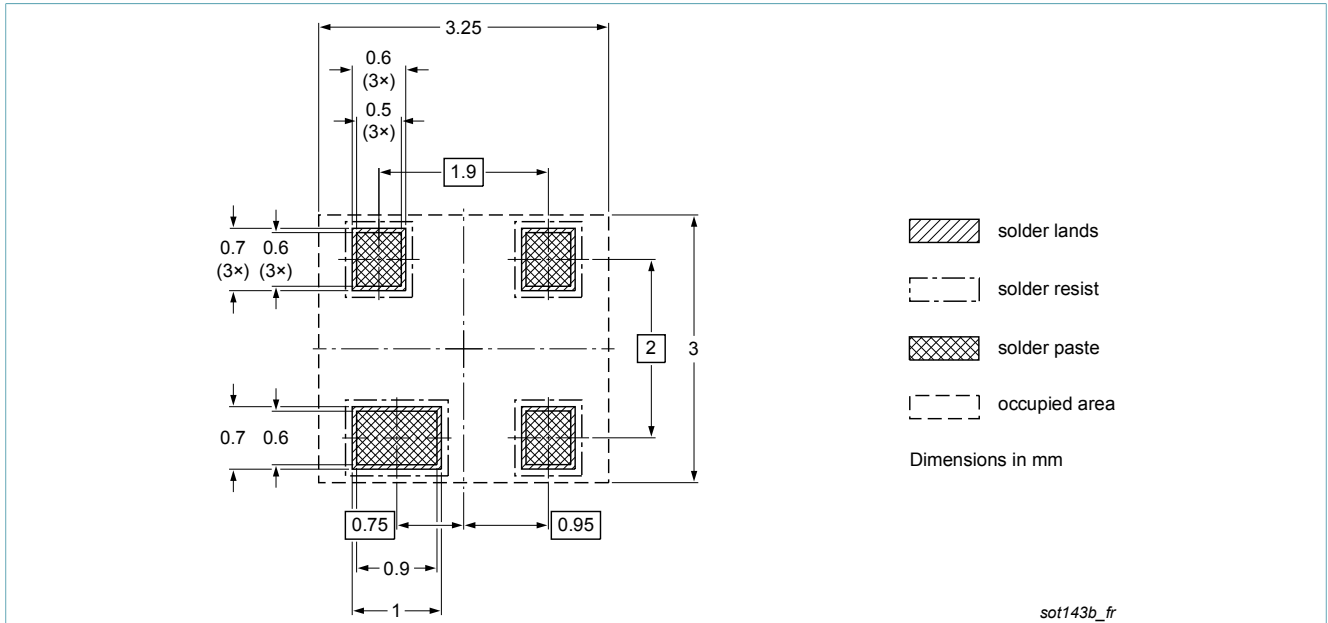


Fig. 2. Reflow soldering footprint for SOT143B

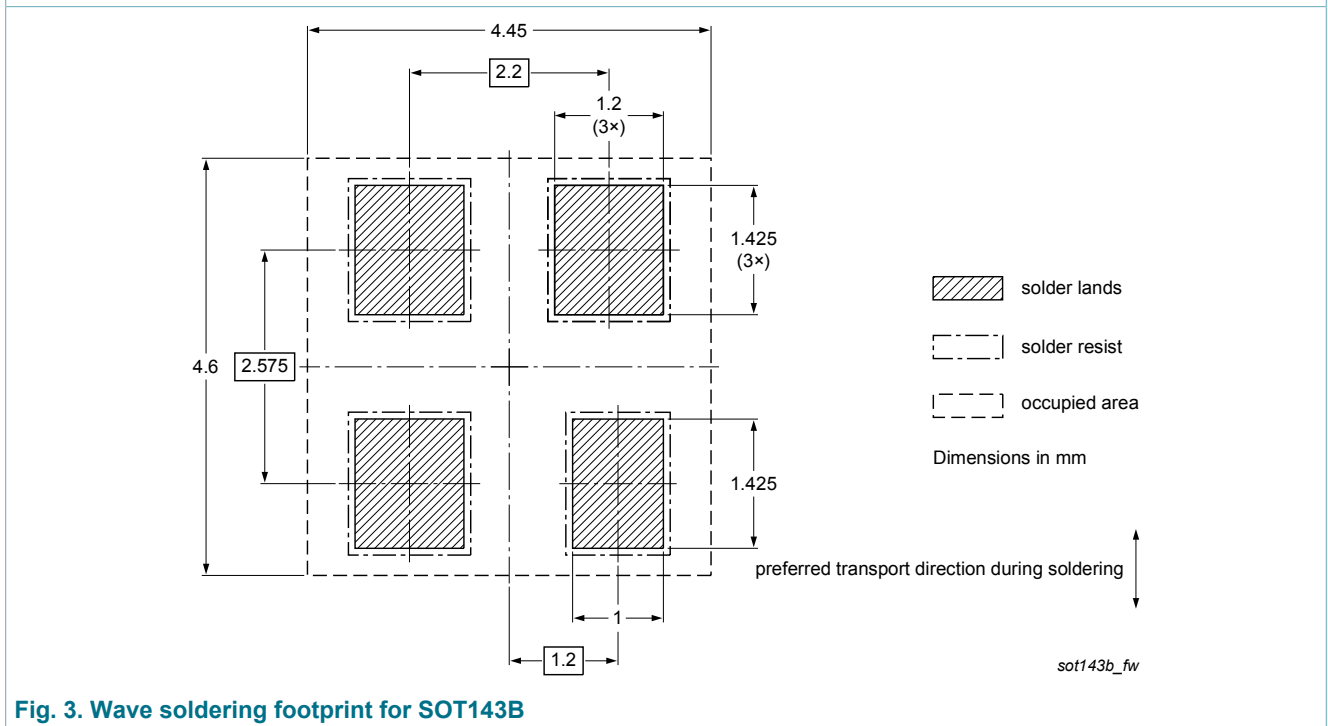


Fig. 3. Wave soldering footprint for SOT143B

4. Legal information

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